T-1 (3mm) TRI-LEVEL LED INDICATOR

Part Number: L-7104SA/3ID

High Efficiency Red

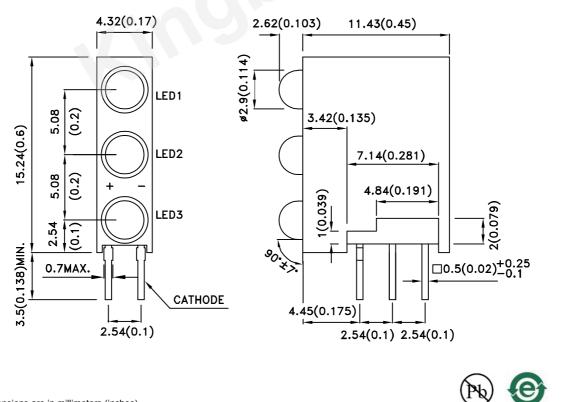
Features

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- · RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



1. All dimensions are in millimeters (inches).

2. Tolerance is ±0.25(0.01") unless otherwise noted.

Lead spacing is measured where the leads emerge from the package.
The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

Notes:

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Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
L-7104SA/3ID	High Efficiency Red (GaAsP/GaP)	Red Diffused	12	30	40°
			*10	*20	

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

627 617 45		nm nm	I⊧=20mA I⊧=20mA
		nm	I⊧=20mA
45			
10		nm	I⊧=20mA
15		pF	VF=0V;f=1MHz
2	2.5	V	IF=20mA
	10	uA	VR = 5V
_	2		

Wavelength: +/-1nm.
Forward Voltage: +/-0.1V.
Wavelength value is traceable to the CIE127-2007 compliant national standards.

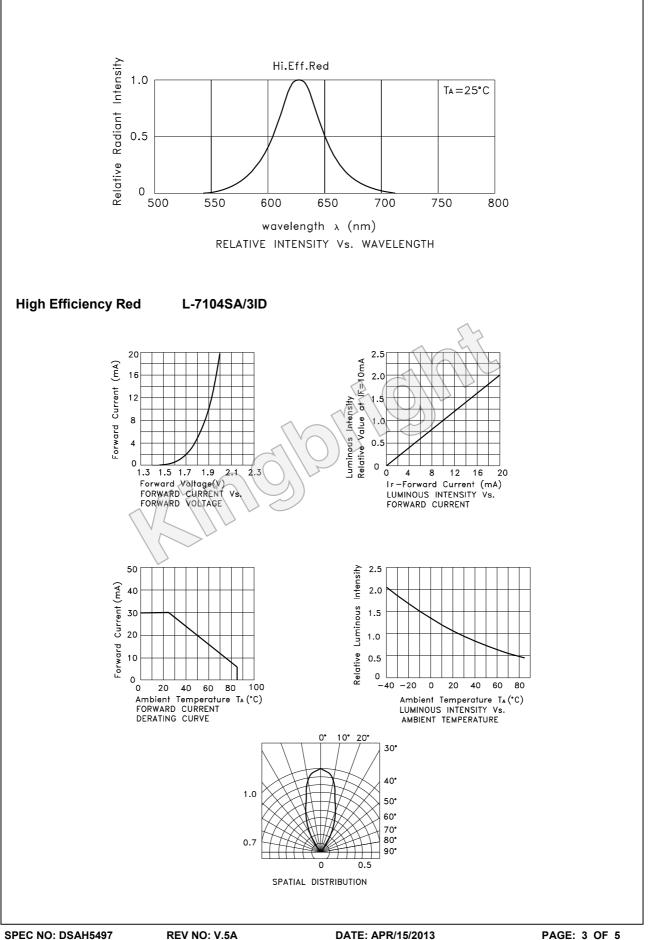
Absolute Maximum Ratings at TA=25°C

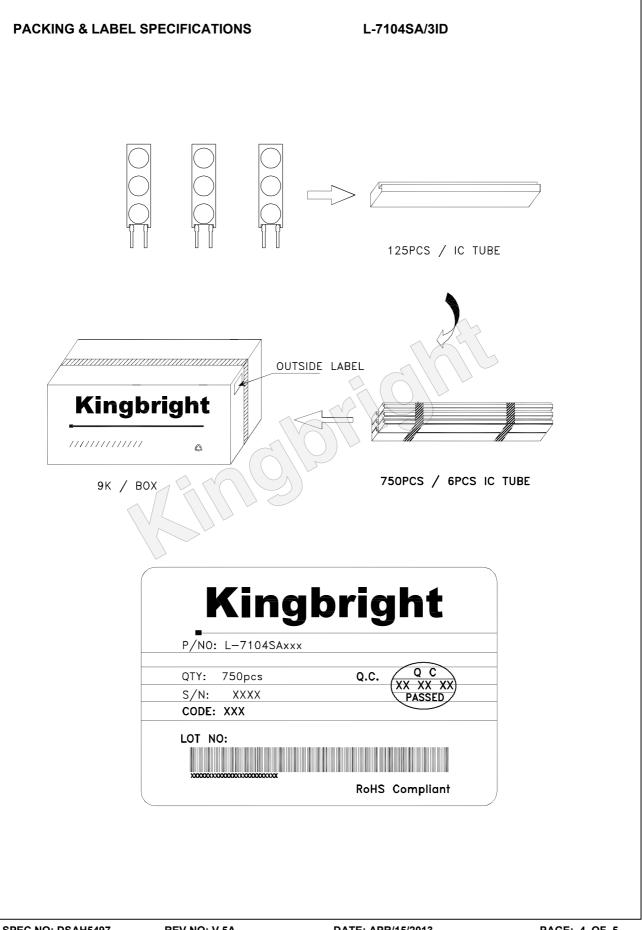
High Efficiency Red	Units		
75	mW		
30	mA		
160	mA		
5	V		
-40°C To +85°C			
260°C For 3 Seconds			
260°C For 5 Seconds			
	75 30 160 5 -40°C To +85°C 260°C For 3 Seconds		

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

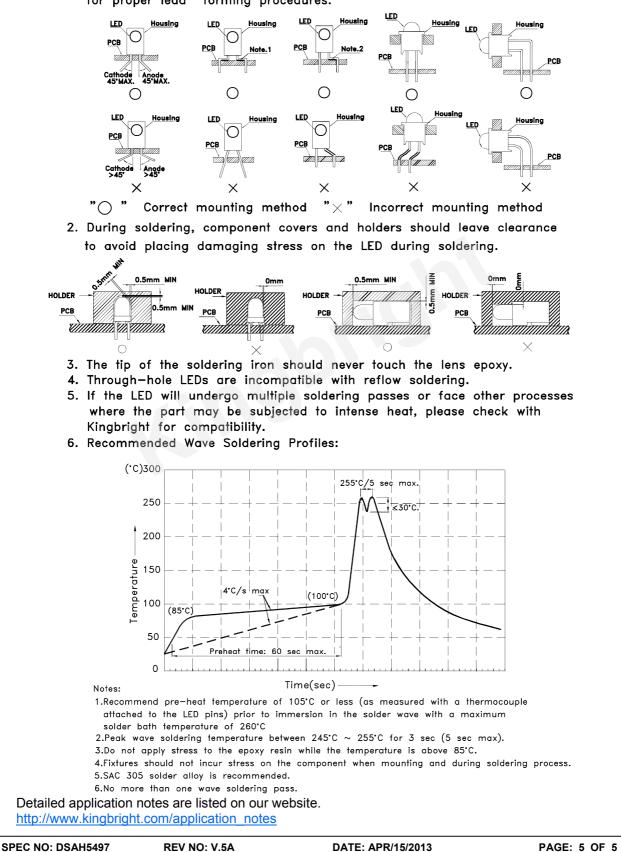
2. 2mm below package base.
3. 5mm below package base.





PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



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